

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YASUAKI AMANO	09/17/2018
SVEN HANSEN	09/24/2018
LENNERT SCHWART	11/01/2018
RECEIVING PARTY DATA	
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City:	GARCHING BEI MUENCHEN
State/Country:	GERMANY
Postal Code:	85748
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16141720
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NAME OF SUBMITTER:	NORMAN P. SOLOWAY
SIGNATURE:	/norman p. soloway/
DATE SIGNED:	11/09/2018
Total Attachments: 3	
source=assignments#page1.tif	
source=assignments#page2.tif	
source=assignments#page3.tif	

ASSIGNMENT

I, Yasuaki AMANO, of Munich, Germany, having invented certain inventions and improvements in **WAFER SUPPORT SYSTEM, WAFER SUPPORT DEVICE, SYSTEM COMPRISING A WAFER AND A WAFER SUPPORT DEVICE AS WELL AS MASK ALIGNER** and having executed an application for Letters Patent of the United States of America describing the same and based thereon (U.S. Patent Application Serial No. 16,141,720, filed September 25, 2018), for good and valuable consideration, the receipt of which is hereby acknowledged from **SUSS MicroTec Lithography GmbH**, a German corporation having its principal place of business at Schleissheimer Strasse 90, 85748 Garching bei Muenchen, Germany (hereinafter called the Assignee), do hereby sell, assign and transfer unto the Assignee, its successors, and assigns my entire right, title, and interest, in and to said invention in the United States of America, including all rights, title and interest in the above-mentioned application and any divisional, continuing or reissue application or applications and any patent which may be issued on the said invention in the United States of America;

And for the same consideration I do agree that I will upon request execute any instrument which the Assignee may desire to carry this Assignment into effect and perfect the title transferred hereby or prosecute the above-mentioned application;

And I do hereby authorize and request the Commissioner/of Patents and Trademarks of the United States of America to issue Letters Patent on the said application to the Assignee;

And I do hereby jointly and severally covenant for myself and for my legal representatives that I have granted no right or license to make, use, or sell said invention to anyone except the Assignee, that prior to the execution of this deed my right, title, and interest in and to said inventions or any of them or any part thereof has not been otherwise encumbered by me, and that I have not executed and will not execute any instrument in conflict herewith.

IN WITNESS WHEREOF, I/we hereunto set my hand and seal on the day and year hereinafter noted.

Inventor's signature  Date Sep. 17th, 2018
Full name (typed or printed) Yasuaki AMANO

Witness: Christian Klotz Witness: _____
Date: Sep. 17th, 2018 Date: _____

ASSIGNMENT

I, Sven HANSEN of Munich, Germany, having invented certain inventions and improvements in **WAFER SUPPORT SYSTEM, WAFER SUPPORT DEVICE, SYSTEM COMPRISING A WAFER AND A WAFER SUPPORT DEVICE AS WELL AS MASK ALIGNER** and having executed an application for Letters Patent of the United States of America describing the same and based thereon (U.S. Patent Application Serial No. 16,141,720, filed September 25, 2018), for good and valuable consideration, the receipt of which is hereby acknowledged from **SUSS MicroTec Lithography GmbH**, a German corporation having its principal place of business at Schleissheimer Strasse 90, 85748 Garching bei Muenchen, Germany (hereinafter called the Assignee), do hereby sell, assign and transfer unto the Assignee, its successors, and assigns my entire right, title, and interest, in and to said invention in the United States of America, including all rights, title and interest in the above-mentioned application and any divisional, continuing or reissue application or applications and any patent which may be issued on the said invention in the United States of America;

And for the same consideration I do agree that I will upon request execute any instrument which the Assignee may desire to carry this Assignment into effect and perfect the title transferred hereby or prosecute the above-mentioned application;

And I do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent on the said application to the Assignee;

And I do hereby jointly and severally covenant for myself and for my legal representatives that I have granted no right or license to make, use, or sell said invention to anyone except the Assignee, that prior to the execution of this deed my right, title, and interest in and to said inventions or any of them or any part thereof has not been otherwise encumbered by me, and that I have not executed and will not execute any instrument in conflict herewith.

IN WITNESS WHEREOF, I/we hereunto set my hand and seal on the day and year hereinafter noted.

Inventor's signature  Date 9/24/2018
Full name (typed or printed) Sven HANSEN

Witness: Christian Kraeh Witness: _____
Date: 9/24/2018 Date: _____

ASSIGNMENT

I, Lennert SCHWART of Munich, Germany, having invented certain inventions and improvements in **WAFER SUPPORT SYSTEM, WAFER SUPPORT DEVICE, SYSTEM COMPRISING A WAFER AND A WAFER SUPPORT DEVICE AS WELL AS MASK ALIGNER** and having executed an application for Letters Patent of the United States of America describing the same and based thereon (U.S. Patent Application Serial No. 16,141,720, filed September 25, 2018), for good and valuable consideration, the receipt of which is hereby acknowledged from **SUSS MicroTec Lithography GmbH**, a German corporation having its principal place of business at Schleissheimer Strasse 90, 85748 Garching bei Muenchen, Germany (hereinafter called the Assignee), do hereby sell, assign and transfer unto the Assignee, its successors, and assigns my entire right, title, and interest, in and to said invention in the United States of America, including all rights, title and interest in the above-mentioned application and any divisional, continuing or reissue application or applications and any patent which may be issued on the said invention in the United States of America;

And for the same consideration I do agree that I will upon request execute any instrument which the Assignee may desire to carry this Assignment into effect and perfect the title transferred hereby or prosecute the above-mentioned application;

And I do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent on the said application to the Assignee;

And I do hereby jointly and severally covenant for myself and for my legal representatives that I have granted no right or license to make, use, or sell said invention to anyone except the Assignee, that prior to the execution of this deed my right, title, and interest in and to said inventions or any of them or any part thereof has not been otherwise encumbered by me, and that I have not executed and will not execute any instrument in conflict herewith.

IN WITNESS WHEREOF, I/we hereunto set my hand and seal on the day and year hereinafter noted.

Inventor's signature  Date 1. 11. 2018
Full name (typed or printed) Lennert SCHWART

Witness:  Witness: _____
Date: 1. 11. 2018 Date: _____